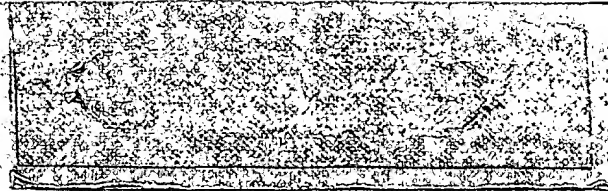


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| | Subclass | ISSUE CLASSIFICATION |
| | Class | |



PATENT NUMBER

U.S. UTILITY Patent Application

105 *DAPE* *ex kw* PATENT DATE
 (PENDING)

| | | | | | |
|------------------------------|-----------------|--------------|-----------------|------------------------|-----------------------------|
| APPLICATION NO. 09/899627 | CONT/PRIOR F | CLASS 438 | SUBCLASS 687 | ART UNIT <i>200</i> | EXAMINER <i>Quarrell</i> |
|------------------------------|-----------------|--------------|-----------------|------------------------|-----------------------------|

APPLICANTS: Jong-won Lee
 Bo-Un Yoon
 Sang-rok Hah

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TITLE: Solution for chemical mechanical polishing and method of manufacturing copper metal interconnection layer using the same.

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PTO-2040 12/99

FORMING CLASSIFICATION
 CLASS 1